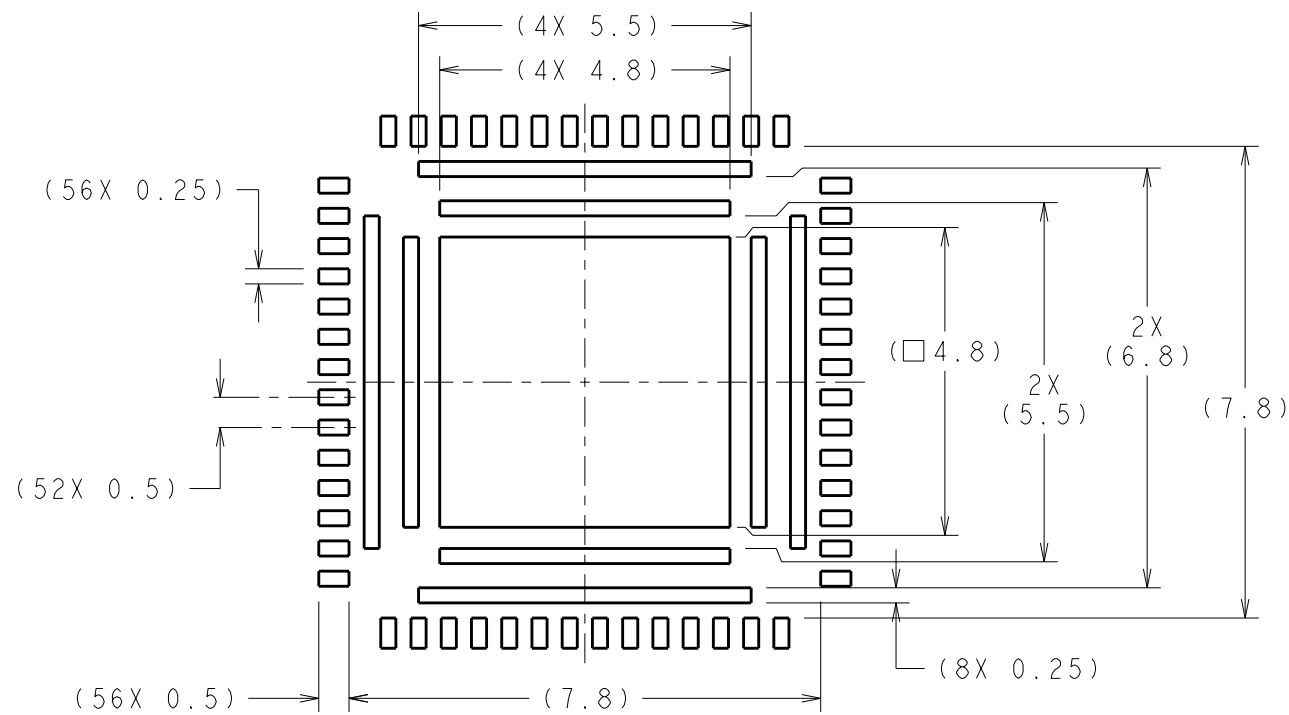
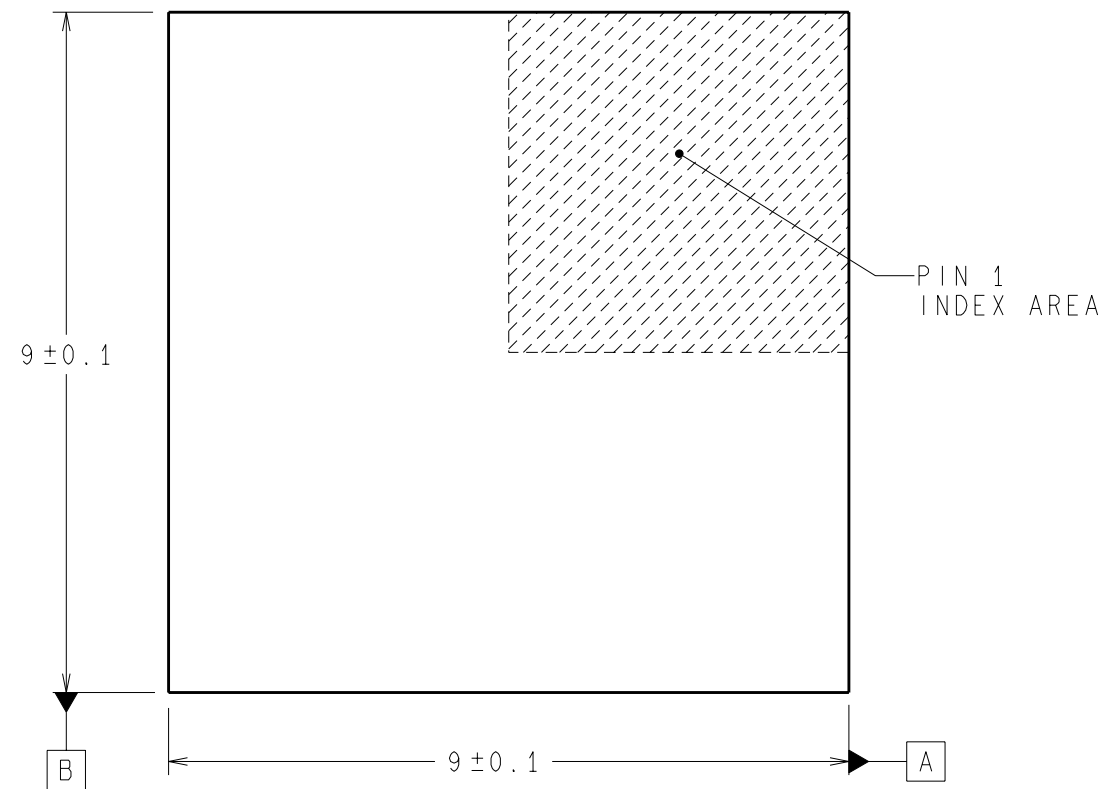


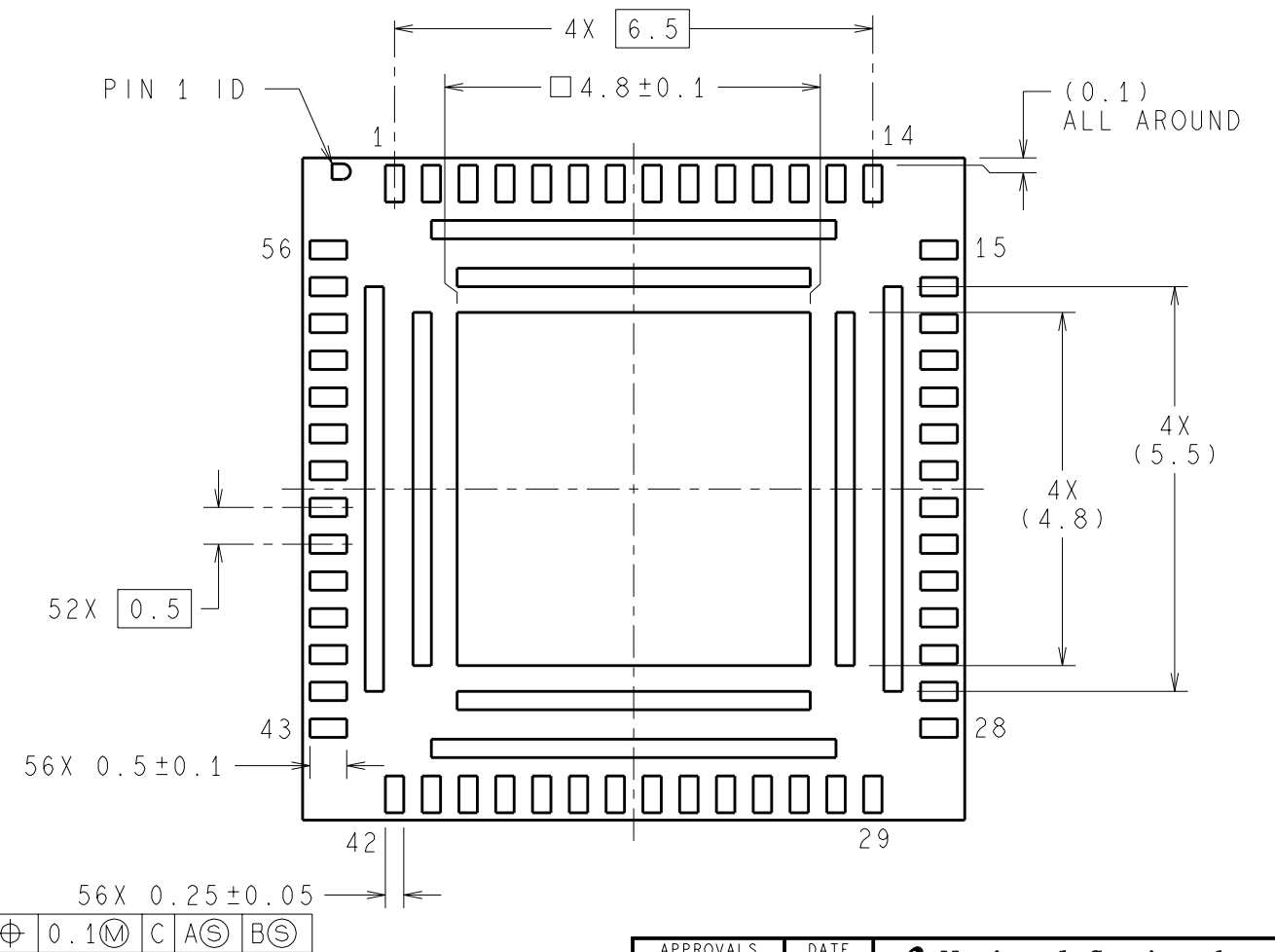
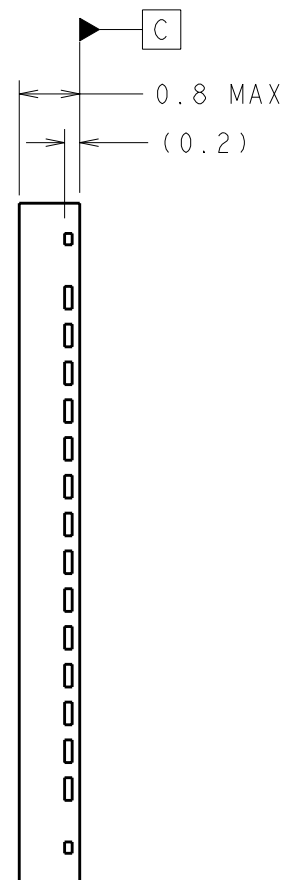
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	208	01/16/2001	TL/JB
B	ADD MISSING DIM'S TO TO LAND PATTERN	448	11/09/2001	TL/JB
C	CORRECT TYPO: 52X 0.5 WAS 56X 0.5; CHANGE DWG FORMAT TO B SIZE	605	04/22/2002	TL/JB
D	ADD LENGTH DIM'S TO PWR & GND RINGS; UPDATE NOTE 2	890	11/26/2002	TL/JB



RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



DIMENSIONS ARE IN MILLIMETERS



NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM LEAD/TIN (SOLDER) ON COPPER.
- NO JEDEC REGISTRATION AS OF NOVEMBER 2002.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090
DRAWN T. LEQUANG		01/16/2001	
DFTG. CHK. MARTA SUCHY		11/26/2002	
ENGR. CHK. JAI ME BAYAN		11/26/2002	
PROJECTION MM			LLP, PLASTIC, QUAD, 9 X 9 X 0.75mm BODY, 56 LD, 0.5mm PITCH, GND & PWR RINGS
SCALE NTS	SIZE B	DRAWING NUMBER (SC)MKT-LQA56A	REV D
FORMERLY: N/A			SHEET 1 of 1